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*(incorporated in the Cayman Islands with limited liability)*  
**(Stock Code: 1360)**

## **SUPPLEMENTAL ANNOUNCEMENT IN RELATION TO THE PLACING OF BONDS**

Reference is made to the announcement of Mega Expo Holdings Limited (the “**Company**”) dated 16 October 2018 (the “**Announcement**”) in relation to the Placing. Unless otherwise defined, terms used in this announcement shall have the same meanings as those defined in the Announcement.

On 5 November 2018 (after trading hours of the Stock Exchange), the Company and the Placing Agent executed a supplemental letter to the Placing Agreement, pursuant to which it was agreed that the maturity date of the Bonds will be revised to a date falling on the second anniversary of the relevant issue date of the Bonds, or if such date is not a Business Day, the Business Day immediately following such date.

Save and except for the aforesaid change, all other terms of the Placing Agreement as disclosed in the Announcement shall remain unchanged.

By Order of the Board  
**Mega Expo Holdings Limited**  
**Deng Zhonglin**  
*Chairman*

Hong Kong, 5 November 2018

*As at the date of this announcement, the Board comprises Mr. Deng Zhonglin and Mr. Xu Feng as executive Directors; and Mr. Choi Hung Fai, Mr. Tsang Wing Ki, Dr. Wong Kong Tin, JP and Mr. Qiu Peiyuan as independent non-executive Directors.*